



Carbon Nanotubes for Interconnects

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Message from the Guest Editors

Dear Colleagues,

Future nanoelectronics technology will be enabled by the effective possibility of complementing the nanoscale devices to the boards, and a major concern is given by the performance of interconnections in nanopackages.

Due to their outstanding physical properties, carbon-based materials are promising candidates for nanointerconnections: In particular, carbon nanotubes have sparked a great deal of interest because of their desirable properties, such as large electron mean free path, mechanical strength, high thermal conductivity, and large current carrying capacity.

This Special Issue is aiming at providing the state-of-the-art on carbon-based interconnections, presenting the most relevant results in modelling, fabrication, and integration, and providing examples of the most recent applications for on-/off-chip interconnections.

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Message from the Editor-in-Chief

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